



Drawing bibliography

3 Characteristic

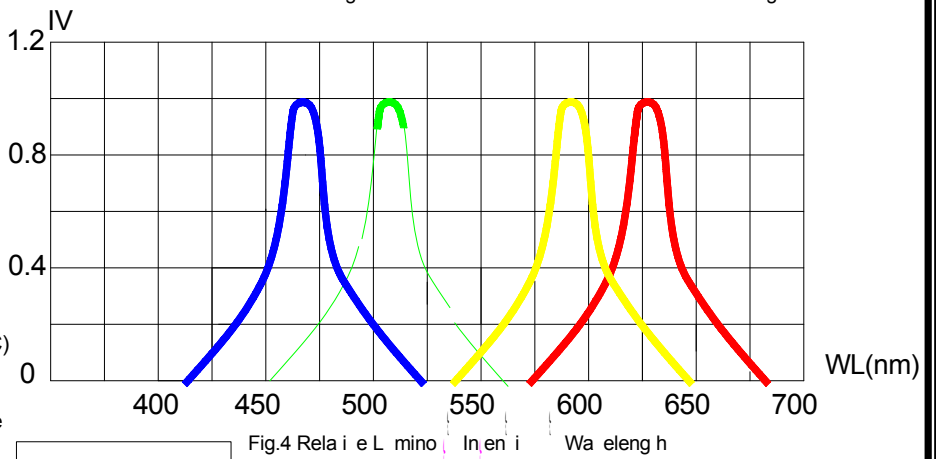
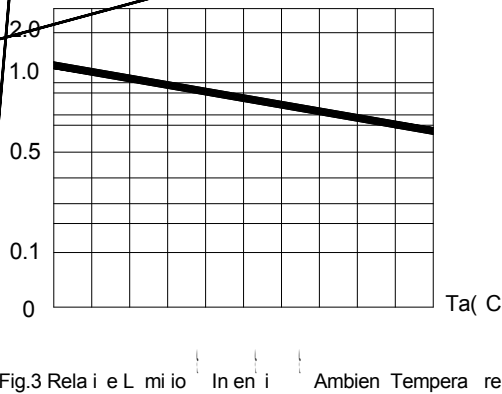
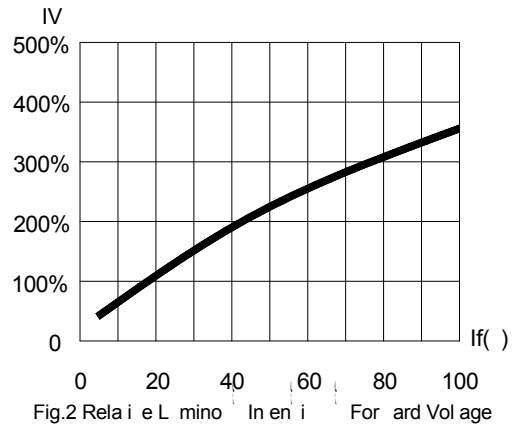
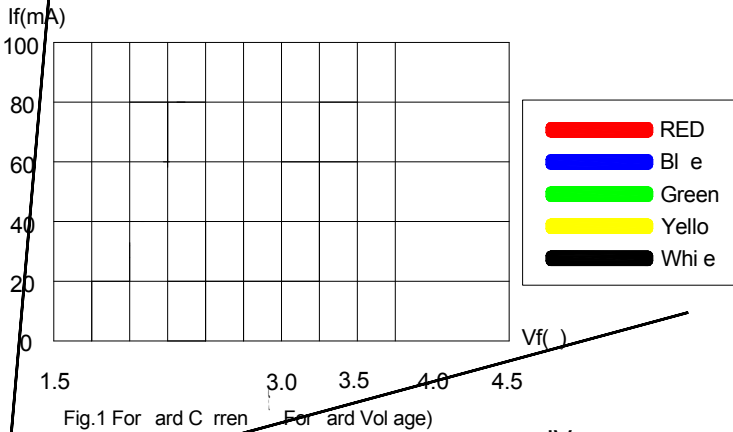
Forward current	If	30	mA
Reverse voltage	Vr	5	V
Power dissipation	Pd	110	mW
Operating temperature range	Top	-25 +80	C
Storage temperature range	Tg	-30 +80	C
Peak pulsed current 1/8 d f=1KH	Ifp	125	mA

Wavelength at peak emission	If=20mA	peak	515	520	525	nm
Spectral half bandwidth	If=20mA			10		
Forward voltage	If=20mA	Vf	3.0	3.4	3.8	V
Minimum luminous intensity	If=20mA	I	3000	4000	5000	mcd
Viewing angle at 50% IV	If=10mA		--	120	--	Deg

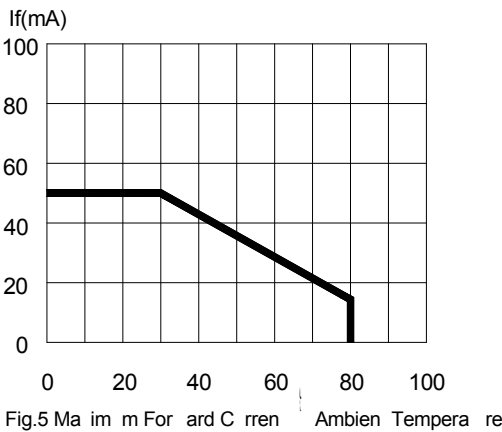
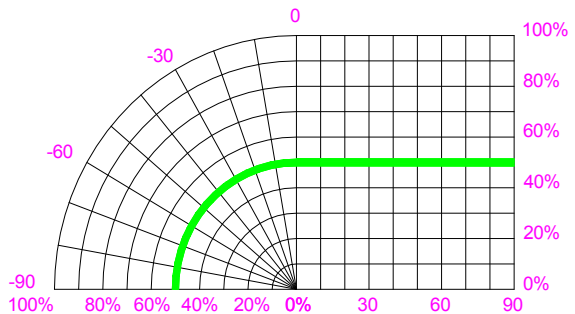


Re er e c rren	Vr=5V	Ir	--	--	5	A
U ef l life	-	IF=20mA	100000			H

Typical Electrical/Optical Characteristic Curve
(Ta=25 Unless Otherwise Noted)



Directional Characteristics





1	Tin-plated	Temp 260 ± 5	5 sec.	76 PCS	0/1
2	Back & forth under high & low temp. in air	High emp. +85 30min to 5min to -55 30min	50 bo	76 PCS	0/1
3	Heating	High emp. +100 30min To 10 sec to -10 30min	50 bo	76 PCS	0/1
4	High temp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low temp.	-55	1000 Hr.	76 PCS	0/1
6	Life span	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Test under high temp. & high humidity	85 ± 2/85%RH	1000 Hr.	76 PCS	0/1

i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position minimum 2mm from board.

ii Dip Soldering: Max temperature is 260 °C, time 5s, the position is minimum 2mm from board.

i Bracket must be bent only 2mm from colloid.

ii Bracket mold must be finished by fire or professional.

iii Bracket mold must be finished before soldering.

i Bracket mold holder are the connection between the pin, the distance gap of lead and the circuit board.

i. It should be paid attention to the ordering of all the devices in case of wrong polarity. Devices can be closed on the heat component, working condition can replace the limit.

ii. It should not assemble LED when the lead are deformed.

iii. When decide on a hole, accurately account the size of hole and hole distance of the line base

i. Suggesting guard heat positioning

i. It should avoid any kind of shake or force on LED, before the soldering temperature return normal.

It should be careful. When clean the board with chemical. Some chemical may bring damage to the surface, and bring color fading, such as, Trichloroethylene, Acetone. Should use ethanol or isopropyl alcohol, dip for no more than 3 minutes under the normal temperature.



7

ଅନୁରାଧା